

Product / Process Change Notice

Parts Affected:

BAV45, Silicon Picoampere diode manufactured in the TO-18 TWO LEADED metal case.

Extent of Change:

The Matte tin (Sn) plating step has been removed from the manufacturing process.

Reason for Change:

To streamline the manufacturing process for the TO-18 TWO LEADED metal case. The TO-18 TWO LEADED header is pre-plated with Gold (Au) 20 μ " minimum over Electrolytic Nickel (Ni) 50 μ " minimum and it was determined that the matte Sn plating step was not necessary.

Effect of Change:

This change does not affect the electrical characteristics of the device.

Qualification:

Solderability testing was performed in accordance with IPC/ECA J-STD-002C with no rejects detected.

Effective Date of Change:

Q2 2011.

Sample Availability:

Please contact Salesperson or Manufacturer's Representative.